

Model 860 Eagle Bonder

for Flip Chips, Laser Diodes/VCSELS and Eutectic Die

The Model 860 Eagle is a multi-use semiautomatic system ideal for R & D and low volume production. Applications include solder and gold bumped flip chip, eutectic bonding including laser diodes and bars and epoxy bonding. Some of the process capabilities that support these applications are ultrasonic, thermosonic, scrub, flux dipping and hot gas spot heating. The system is designed for maximum versatility and ease of operation.

Available Features

Cube beam splitter viewing system with LED array illumination which includes computer control of the LEDs allowing multiple light settings to be stored in macros for different applications.

Color CCD camera with enhanced resolution and 19" LCD Color display including video overlays and image capture.

Motorized viewer option provides 5/8" travel from center in X and Y to facilitate aligning large devices.

Direct viewing microscope with ring illuminator on pivoting mount for laser diode applications.

Side-view camera and lens for in-process viewing.

External PC with Windows XP Pro operating system, hard drive, CD drive, floppy drive, network card, USB ports, keyboard, and mouse.

Precision servo-driven Z motion with closed loop bond load control and loads from 10 grams to 10KG.

In-process planarity adjust for either single or dual axis. Allows operator to level the stage within 1-2 microns.

Real time graphic display of closed loop temperature controls for head, stage and spot heating.

Single and dual hot gas spot heating.

Servo-controlled voice coil-driven ultra fine linear scrub bond head. Returns to origin within microns.

Ultrasonic option to 3 KG.

Anti-vibration table with compact footprint.

Automatic precision translation table.

Die presentation for 2" and 4" sq. waffle or gel packs. Custom trays available.

Heated die tool to 350 degrees C.



Specifications

Aligns and attaches die sizes up to 2.0" sq.

Placement accuracy +/- 0.5 um

Magnification up to 560X.

Field of view up to 1.20" diagonal.

Choice of heated stages from 3/4" rapid heat to 4.0" fixed temperature stage. Custom stages available.



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